

IRF9530PbF

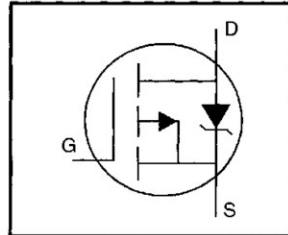
HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

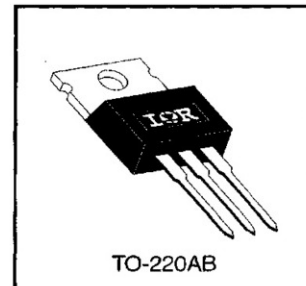
The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



$$V_{DS} = -100V$$

$$R_{DS(on)} = 0.30\Omega$$

$$I_D = -12A$$



Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10 V$	-12	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10 V$	-8.2	
I_{DM}	Pulsed Drain Current ①	-48	
$P_D @ T_C = 25^\circ C$	Power Dissipation	88	W
	Linear Derating Factor	0.59	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	400	mJ
I_{AR}	Avalanche Current ①	-12	A
E_{AR}	Repetitive Avalanche Energy ①	8.8	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.5	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	

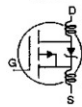
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	1.7	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62	

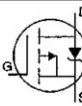
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International
IR Rectifier

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-100	—	—	V	$V_{GS}=0V$, $I_D=-250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.10	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=-1mA$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.30	Ω	$V_{GS}=-10V$, $I_D=-7.2A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS}=V_{GS}$, $I_D=-250\mu A$
g_{fs}	Forward Transconductance	3.7	—	—	S	$V_{DS}=-50V$, $I_D=-7.2A$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	-100	μA	$V_{DS}=-100V$, $V_{GS}=0V$
		—	—	-500		$V_{DS}=-80V$, $V_{GS}=0V$, $T_J=150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS}=-20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS}=20V$
Q_g	Total Gate Charge	—	—	38	nC	$I_D=-12A$
Q_{gs}	Gate-to-Source Charge	—	—	6.8		$V_{DS}=-80V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	21		$V_{GS}=-10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	12	—	ns	$V_{DD}=-50V$
t_r	Rise Time	—	52	—		$I_D=-12A$
$t_{d(off)}$	Turn-Off Delay Time	—	31	—		$R_G=12\Omega$
t_f	Fall Time	—	39	—		$R_D=3.9\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact 
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	860	—	pF	$V_{GS}=0V$
C_{oss}	Output Capacitance	—	340	—		$V_{DS}=-25V$
C_{rss}	Reverse Transfer Capacitance	—	93	—		$f=1.0MHz$ See Figure 5

Source-Drain Ratings and Characteristics

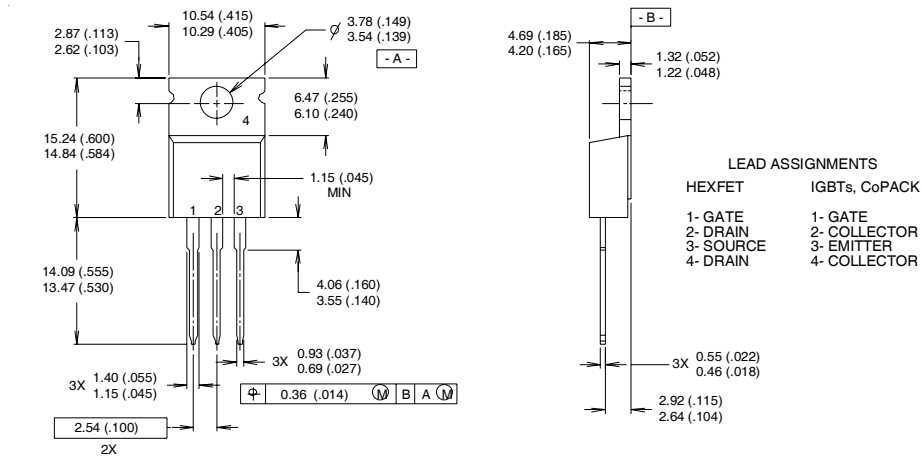
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-12	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-48		
V_{SD}	Diode Forward Voltage	—	—	-6.3	V	$T_J=25^\circ\text{C}$, $I_S=-12A$, $V_{GS}=0V$ ④
t_{rr}	Reverse Recovery Time	—	120	240	ns	$T_J=25^\circ\text{C}$, $I_F=-12A$
Q_{rr}	Reverse Recovery Charge	—	0.46	0.92	μC	$di/dt=100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ② $V_{DD}=-25V$, starting $T_J=25^\circ\text{C}$, $L=4.2mH$, $R_G=25\Omega$, $I_{AS}=-12A$ (See Figure 12)
- ③ $I_{SD}\leq -12A$, $di/dt\leq 140A/\mu s$, $V_{DD}\leq V_{(BR)DSS}$, $T_J\leq 175^\circ\text{C}$
- ④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
 - 2 CONTROLLING DIMENSION : INCH
 - 3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.
 - 4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010
 LOT CODE 1789
 ASSEMBLED ON WW 19, 1997
 IN THE ASSEMBLY LINE "C"
Note: "P" in assembly line position indicates "Lead-Free"

